

敬 承  
CUSTOMER:

规 格 书

SPECIFICATION FOR APPROVAL

品名规格 (DESCRIPTION): TF CARD PUSH PUSH 1.85H CONN

客户料号 (CU PART NO.):

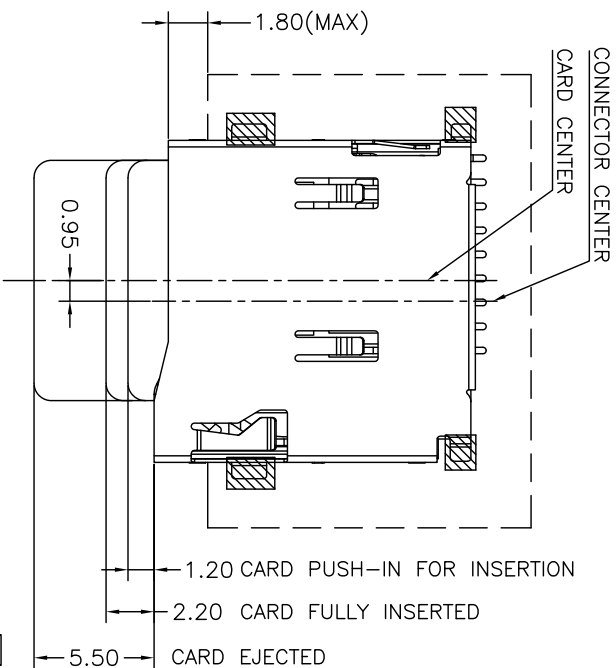
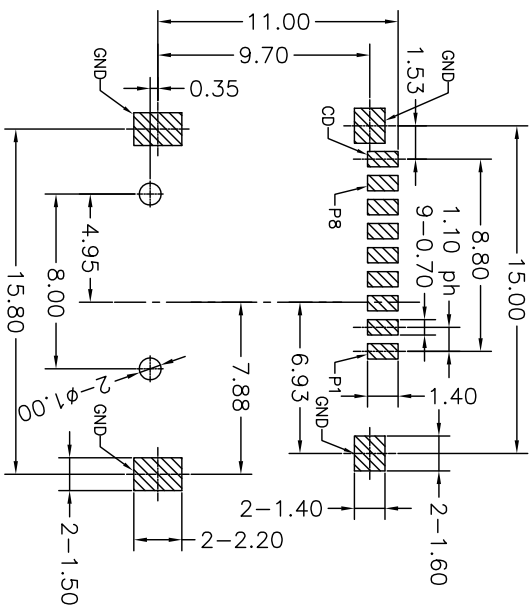
轻 平 料 号 (PART NO.): FTF01-091XX0X-002

送 样 日 期 (DATE):

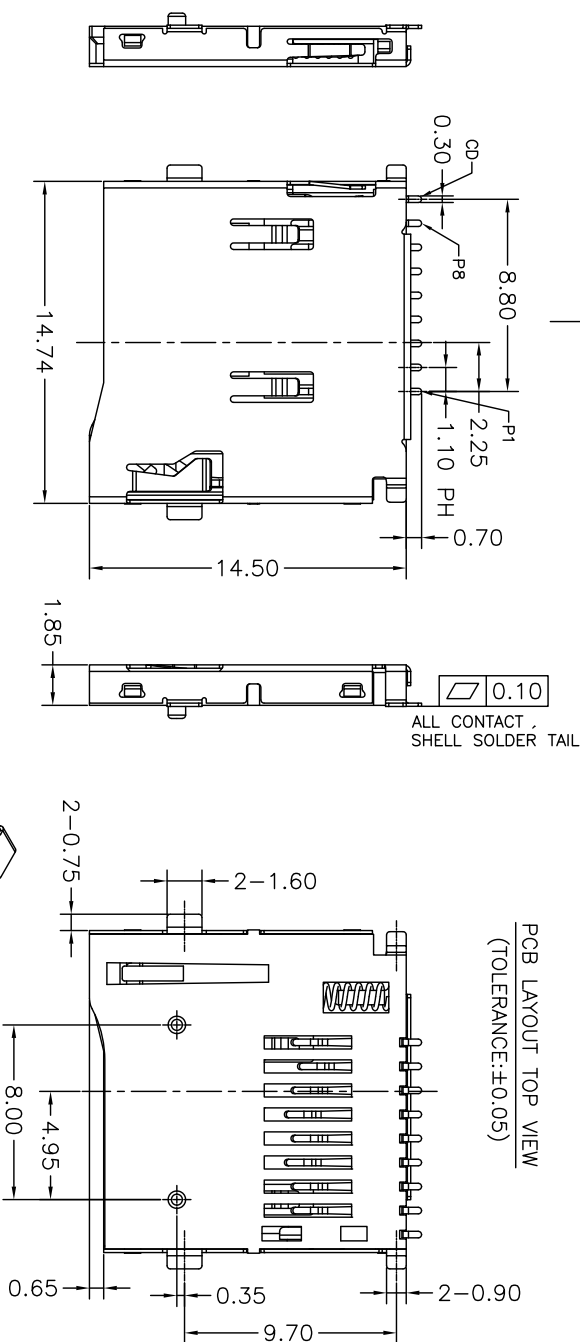
| 客 户 回 签       |                |                | 轻 平 电 子       |                |                |
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| 品质部<br>QC DEP | 工程部<br>ENG DEP | 采购部<br>PUR DEP | 品质部<br>QC DEP | 工程部<br>ENG DEP | 采购部<br>PUR DEP |
|               |                |                |               |                |                |

东莞市轻平电子科技有限公司 Dongguan Qingping Electronic Technology Co., Ltd.

| REV | ECN/NO | REVISION NOTE | DATE       | SIGNATURE |
|-----|--------|---------------|------------|-----------|
| A   | ND     | RELEASED      | 2015.01.10 | A-ZONG    |



PCB LAYOUT TOP VIEW  
(TOLERANCE:±0.05)



- SPECIFICATION
- 1.ELECTRICAL CHARACTERISTICS:
- CONTACT CURRENT RATING:0.5 AMPERES.
- DIELECTRIC WITHSTANDING VOLTAGE:AC500V.R.M.S.
- INSULATION RESISTANCE:1000MΩ MINIMUM.
- CONTACT RESISTANCE:100mΩ MAXIMUM.
- 2.MECHANICAL CHARACTERISTICS:
- MATING CYCLES:5,000 INSERTIONS.
- INSERTION FORCE: 2.0KGf MAX.
- EXTRACTION FORCE: 0.4KGf MIN.
- 3.ENVIRONMENTAL:
- OPERATING TEMPERATURE:-20℃~+85℃.
- 3.MATERIAL:
- HOUSING:HI-TEMP PLASTIC LCP UL 94V-D RATED
- SLIDER:HI-TEMP PLASTIC LCP UL 94V-D RATED
- CONTACT:COOPER ALLOY(CT=0.15MM).
- SHELL:STAINLESS STEEL(CT=0.15MM).
- DRAW LINK:STAINLESS STEEL(Φ0.30MM).
- SPRING:SWP
- 4.PART NO:
- FTF01 - 09 1 X X 0 X - 002

PIN Q'TY: 9 PIN

PACKING OPTION

TRIPLE

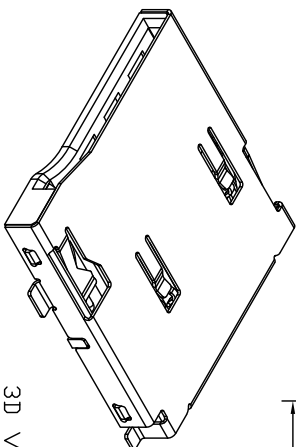
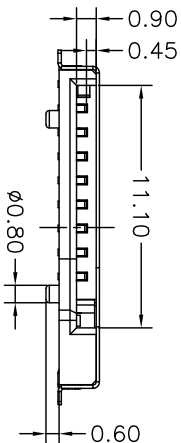
- TERMINAL PLATING:
- A 10 G/F MATTE SN
- B 30 G/F MATTE SN
- C 50 G/F MATTE SN
- D 150 G/F MATTE SN
- E 300 G/F MATTE SN
- 1 10 G/F OVER ALL
- 2 30 G/F OVER ALL
- 3 50 G/F OVER ALL
- 4 150 G/F OVER ALL
- 5 300 G/F OVER ALL
- SHELL PLATING:
- A 10 G/F ON THE SOLDER
- B 30 G/F ON THE SOLDER
- C 50 G/F ON THE SOLDER
- D 150 G/F ON THE SOLDER
- E 300 G/F ON THE SOLDER
- N 500 NI PLATING OVER ALL



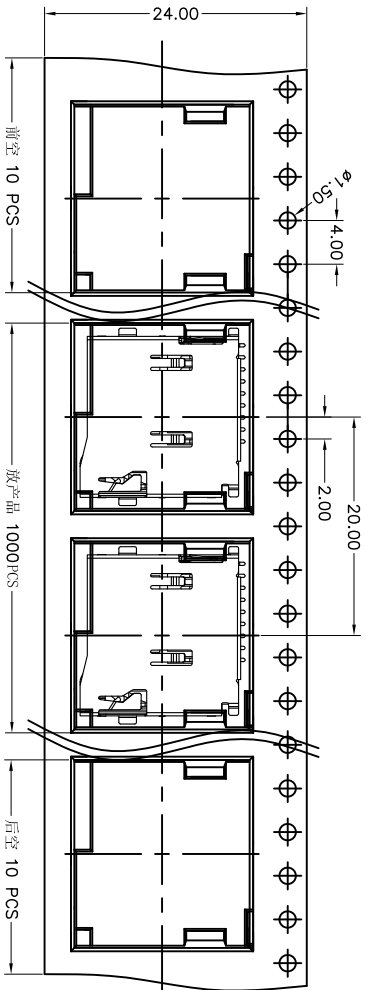
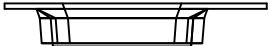
东莞市轻平电子科技有限公司

| DIMENSION UNIT MM                    |         |  | 东莞市轻平电子科技有限公司                                                                      |
|--------------------------------------|---------|-------------------------------------------------------------------------------------|------------------------------------------------------------------------------------|
| TOLERANCE UNLESS OTHERWISE SPECIFIED |         |                                                                                     |                                                                                    |
| .X±0.30                              | .X±3°   | APR.                                                                                | TITLE<br>TF CARD PUSH PUSH 185H CONN                                               |
| .XX±0.20                             | .XX±2°  | CHK.<br>A-Zong                                                                      | PRD.                                                                               |
| .XXX±0.10                            | .XXX±1° | DRA.<br>A-Zong_chen                                                                 |  |
| SHEET: 1/2                           |         | SCALE: 1:1                                                                          | REV: A/1                                                                           |

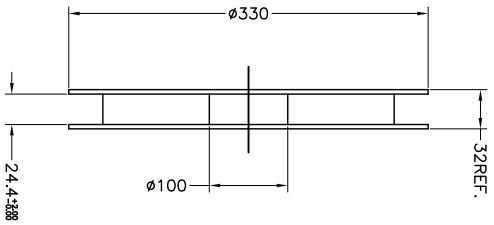
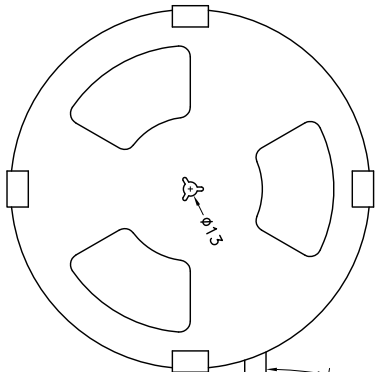
3D VIEW



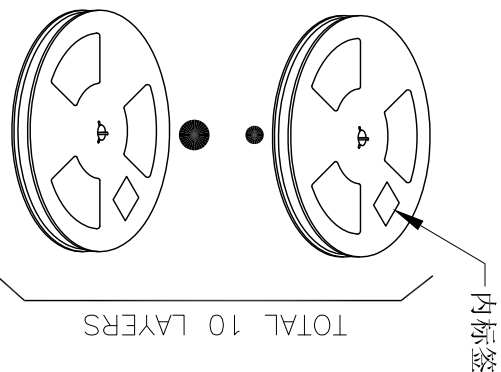
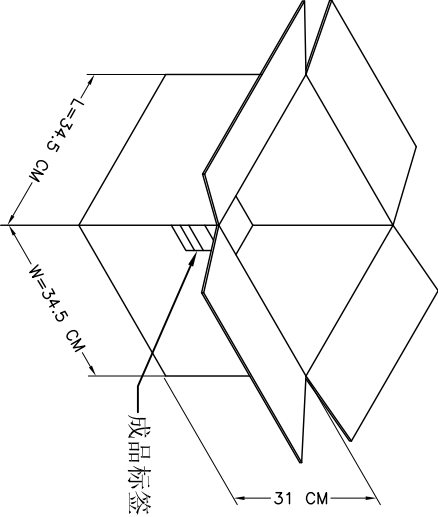
| REV | ECNNO | REVISION NOTE | DATE       | SIGNATURE |
|-----|-------|---------------|------------|-----------|
| A   | ND    | RELEASED      | 2015.01.10 | A-ZONG    |



1. 材质要求:
- 1.1 纸箱的材质要求为B=B; 外形尺寸为 34.5\*34.5\*31CM;
  - 1.2 卷盘的材质为PS; 卷盘的外形尺寸为 $\phi 330 \times 32$ ;
  - 1.3 载带的材质为PS; 卷带规格 24 MM \* 20.4 M
2. 包装要求:
- 2.1 将卷带放入包装机后, 前空10 PCS, 后放产品 1000 PCS, 再后空10 PCS;
  - 2.2 将包装好的产品从包装机上取下并包装好;
  - 2.3 把累叠好的10盘叠放入纸箱中共计10000 PCS;
  - 2.4 把包装好的成品打包封箱, 并在纸箱外贴上标签



PEEL OFF DIRECTION



| DIMENSION UNIT MM                    |         |  | 东莞市轻平电子科技有限公司                                                                              |
|--------------------------------------|---------|-------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------|
| TOLERANCE UNLESS OTHERWISE SPECIFIED |         |                                                                                     |                                                                                            |
| .X±0.30                              | .X±3°   | APR.                                                                                | TITLE:<br><br>TF CARD PUSH PUSH 1.85H CONN                                                 |
| .XX±0.20                             | .XX±2°  | CHK:<br>A-Zong                                                                      | PRD.<br> |
| .XXX±0.10                            | .XXX±1° | DRA.<br>A-Zong_chen                                                                 | PART_NUMBER: FTF01-091XXXX-XXX<br>FILE NO.<br>SHEET: 2/2 SCALE: 2:1 REV: A/1               |

东莞市轻平电子科技有限公司

TITLE: TF CARD PUSH PUSH 185H CONN

|   |   |   |   |   |   |   |   |
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| 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 |
| 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 |

| Part Number       | Product Name           | Rev | Page No |
|-------------------|------------------------|-----|---------|
| FTFXX-XXXXXXX-XXX | TF card push connector | A   | 1/9     |

# PRODUCT SPECIFICATION

| Revision date |      | Pages       | Rev | Revision content |              |        |
|---------------|------|-------------|-----|------------------|--------------|--------|
| 2015/1/15     |      | 7           | A   | NEW              |              |        |
|               |      |             |     |                  |              |        |
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|               |      |             |     |                  |              |        |
| Approved by:  | Zeng | Checked by: |     | JianZhong.Chen   | Prepared by: | A-Zong |

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Dongguan Qingping Electronic Technology Co., Ltd.

| Part Number                                         |      | Product Name           |                 | Rev          | Page No |
|-----------------------------------------------------|------|------------------------|-----------------|--------------|---------|
| FTFXX-XXXXXXX-XXX                                   |      | TF card push connector |                 | A            | 2/9     |
| DIRECTORY                                           |      |                        |                 |              |         |
| 1. SCOPE.....3                                      |      |                        |                 |              |         |
| 2. REFERENCE DOCUMENTS.....3                        |      |                        |                 |              |         |
| 3. FEATURE & DIMENSIONS.....3                       |      |                        |                 |              |         |
| 3. 1. PRODUCT DIMENSION.....3                       |      |                        |                 |              |         |
| 3. 2. PCB/PANEL LAYOUT.....3                        |      |                        |                 |              |         |
| 3. 3. MATERIAL.....3                                |      |                        |                 |              |         |
| 3. 4. MECHANICAL & ELECTRICAL CHARACTERISTIC.....3  |      |                        |                 |              |         |
| 3. 5. PACKAGING.....3                               |      |                        |                 |              |         |
| 3. 6. MARKING.....3                                 |      |                        |                 |              |         |
| 3. 7. TRANSPORTATION.....3                          |      |                        |                 |              |         |
| 3. 8. STORAGE.....4                                 |      |                        |                 |              |         |
| 4. ENVIRONMENTAL.....4                              |      |                        |                 |              |         |
| 4. 1. SOLDERABILITY.....4                           |      |                        |                 |              |         |
| 4. 2. RESISTANCE TO SOLDER HEAT.....4               |      |                        |                 |              |         |
| 4. 2. 1. Wave Soldering.....4                       |      |                        |                 |              |         |
| 4. 2. 1. 1. Preheat.....4                           |      |                        |                 |              |         |
| 4. 2. 1. 2. Soldering.....4                         |      |                        |                 |              |         |
| 4. 2. 1. 3. Cool Down .....4                        |      |                        |                 |              |         |
| 4. 2. 2. INFRARED REFLOW.....4                      |      |                        |                 |              |         |
| 4. 2. 2. 1. Preheat.....4                           |      |                        |                 |              |         |
| 4. 2. 2. 2. Soldering.....4                         |      |                        |                 |              |         |
| 4. 2. 2. 3. Cool Down.....4                         |      |                        |                 |              |         |
| 4. 3. CLEANING.....4                                |      |                        |                 |              |         |
| 5. PERFORMANCE AND TEST DESCRIPTION.....5           |      |                        |                 |              |         |
| 5. 1. REQUIREMENT.....5                             |      |                        |                 |              |         |
| 5. 2. TEST CONDITION.....5                          |      |                        |                 |              |         |
| 5. 3. SAMPLE SELECTION.....5                        |      |                        |                 |              |         |
| 5. 4. TEST SEQUENCE.....5                           |      |                        |                 |              |         |
| 6. QUALITY ASSURANCE PROVISIONS.....5               |      |                        |                 |              |         |
| TABLE I: PERFORMANCE REQUIREMENTS.....6             |      |                        |                 |              |         |
| TABLE II: PRODUCT QUALIFICATION TEST SEQUENCE.....8 |      |                        |                 |              |         |
| TABLE III: REFLOW SOLDERING PROFILE.....9           |      |                        |                 |              |         |
| Approved by:                                        | Zeng | Checked by:            | JianZhong. Chen | Prepared by: | A-Zong  |

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| Part Number                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                              | Product Name           | Rev         | Page No        |              |        |
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| FTFXX-XXXXXXX-XXX                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                        | TF card push connector | A           | 3/9            |              |        |
| <p>1. SCOPE</p> <p>This product specification defines the product performance and the test methods to ascertain the performance of the TF Memory card push connector. which is designed and manufactured by Yconn</p> <p>2. REFERENCE DOCUMENTS</p> <p>MIL-STD-1344A Test method for electrical connector MIL-STD-202F Test method for electrical components EIA364 Test method for electrical components JIS C 0051 Test method for electrical components</p> <p>MIL-G-45204C Specification for gold plating IEC-512-3 IEC standard for current carrying capacity tests QQ-N-290A Specification for nickel plating MIL-P-81728A Specification for tin/lead plating MIL-T-10727B Specification for tin plating UL498 UL standard for safety of attachment plug and receptacle EN/ISO5961 Determination of total lead &amp; cadmium content EN1122 Determination of total lead &amp; cadmium content EN13346 Determination of heavy metals content EPA3052 Determination of total lead &amp; cadmium content</p> <p>3. FEATURE &amp; DIMENSIONS</p> <p>3.1. PRODUCT DIMENSION</p> <p>These connectors shall have the dimensions as shown in customer drawing.</p> <p>3.2. PCB/PANEL LAYOUT</p> <p>The recommended PCB layout is shown in customer drawing.</p> <p>3.3. MATERIAL</p> <p>3.3.1. HOUSING: H1-TEMP PLASTIC LCP UL 94V-0 RATED</p> <p>3.3.2. CANTACT: COPPER ALLOY (T=0.15MM)</p> <p>3.3.3. SHELL: STAINLESS STEEL (T=0.15MM)</p> <p>The harmful material can follow the requirement of RoHS.</p> <p>3.4. MECHANICAL &amp; ELECTRICAL CHARACTERISTIC</p> <p>The connector shall have the mechanical and electrical performance as described in table I:</p> <p>3.5. PACKAGING</p> <p>Products shall be packaged according to requirements specified in purchase order for safe delivery. Products required tray or carrier tape should meet the proper specification per purchase order. Connector container and the packaging specification is shown in customer drawing.</p> |                        |             |                |              |        |
| Approved by:                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                             | Zeng                   | Checked by: | JianZhong.Chen | Prepared by: | A-Zong |

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| Part Number                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                    | Product Name           | Rev         | Page No        |              |        |
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| FTFXX-XXXXXXX-XXX                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                              | TF card push connector | A           | 4/9            |              |        |
| <p>3.6. MARKING</p> <p>Manufacturer’ s name, industry recognized logo, or customer approved marks.</p> <p>3.7. TRANSPORTATION</p> <p>Any vehicle can be adopted for the transportation, but moisture-proof and no mechanical damage.</p> <p>3.8. STORAGE</p> <p>Temperature: -25℃~+90℃, Relative humidity: ≤80%, Not to storage in corrosive environments</p> <p>A re-qualification test shall be conducted immediately while the storage duration exceed 6 months.</p> <p>4. ENVIRONMENTAL</p> <p>4.1. SOLDERABILITY</p> <p>Connector ’ s solderability can meet MIL-STD-202F standard. Finish shall be free of contaminants.</p> <p>4.2. RESISTANCE TO SOLDER HEAT</p> <p>4.2.1. Wave Soldering</p> <p>Consists of three consecutive phases.</p> <p>4.2.1.1. Preheat</p> <p>Increase in temperature not to exceed 4℃ per second. Final preheat temperature will be within 125℃of solder temperature..</p> <p>4.2.1.2. Soldering</p> <p>Device leads will be exposed to solder wave at 260℃for a maximum of 5 seconds.</p> <p>4.2.1.3. Cool Down</p> <p>Cool down in ambient air at approximately 20℃to 25℃.</p> <p>4.2.2. INFRARED REFLOW</p> <p>Three cycles. Each cycle consisting of three consecutive phased.</p> <p>4.2.2.1. Preheat</p> <p>Increase in temperature not to exceed 4℃ per second.</p> <p>4.2.2.2. Soldering</p> <p>Maximum allowable time above reflow temperature of 183℃ is 90 seconds. Maximum temperature</p> <p>4.2.2.3. Cool Down</p> <p>Cool down shall not exceed 6℃ per second. Note:Device temperature measurements are reference</p> <p>4.3. CLEANING</p> <p>Connectors resist to cleaning process. Aqueous Cleaning: Three cycles; each cycle consisting</p> |                        |             |                |              |        |
| Approved by:                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                   | Zeng                   | Checked by: | JianZhong.Chen | Prepared by: | A-Zong |

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| Part Number                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                 | Product Name           | Rev         | Page No        |              |        |
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| FTFXX-XXXXXXX-XXX                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           | TF card push connector | A           | 5/9            |              |        |
| <p>5. Ratings</p> <p>5.1. Current Rating : 0.5A</p> <p>5.2. Voltage Rating : 5V</p> <p>5.3 Voltage:AC 500V R.M.S.</p> <p>5.4. Operating temperature : −20℃ to +85℃</p> <p>Humidity : 90% max. non condensing。</p> <p>6. PERFORMANCE AND TEST DESCRIPTION</p> <p>6.1. REQUIREMENT</p> <p>Product is designed to meet electrical, mechanical, and environmental performance requirements specified in Table I.</p> <p>6.2. TEST CONDITION</p> <p>Unless otherwise specified, all tests shall be performed at ambient environmental conditions.</p> <p>6.3. SAMPLE SELECTION</p> <p>Test samples shall be selected at random from current production. No test samples shall be reused. Samples are pre-conditioned with 10cycles of durability. Each group shall be containing 5 test samples.</p> <p>6.4. TEST SEQUENCE</p> <p>Products qualification test sequence as shown in Table II.</p> <p>7. QUALITY ASSURANCE PROVISIONS</p> <p>Yconn is responsible for the quality of the part as it is delivered to customer. Failing lots will be return or other supplier corrective action.</p> |                        |             |                |              |        |
| Approved by:                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                | Zeng                   | Checked by: | JianZhong.Chen | Prepared by: | A-Zong |

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| Part Number                              |      | Product Name                                                                                                           |             | Rev                                                                                                                                                                                | Page No             |
|------------------------------------------|------|------------------------------------------------------------------------------------------------------------------------|-------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------|
| FTFXX-XXXXXXX-XXX                        |      | TF card push connector                                                                                                 |             | A                                                                                                                                                                                  | 6/9                 |
| TABLE I: PERFORMANCE REQUIREMENTS        |      |                                                                                                                        |             |                                                                                                                                                                                    |                     |
| 1. Confirmation of Product               |      | Product shall be conforming to the requirements of applicable product drawing.                                         |             | Visually, dimensions and functionally inspected per applicable product drawing.                                                                                                    |                     |
| 2. Contact resistance (Low Level)        |      | 100 mΩ Max                                                                                                             |             | Subject mated contacts assembled in housing to closed circuit of 100 mA max. at open circuit voltage of 20 mV max.                                                                 |                     |
| 3. Insulation resistance                 |      | 1000 MΩ Min.                                                                                                           |             | Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connector. MIL-STD-202, Method 302, Condition B (500 V DC±10%). |                     |
| 4. Dielectric Strength                   |      | Connector must withstand test potential of 500 V AC for 1 minute. Current leakage must be 1.0 mA max..                 |             | Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connector. MIL-STD-202, Method 301.                             |                     |
| 5. Durability (Repeated Mating/Unmating) |      | Contact Resistance: 100 mΩ Max. And insertion/extraction force must meet the association specification. After testing. |             | Mate and un-mate connector for 5000cycle. The insertion force under 2.0Kg Max, and the extraction force meet 0.4kg Min, mate and unmated connectors for 300 cycles per hour.       |                     |
| 6. Temperature rise                      |      | 30° C Max.                                                                                                             |             | Carry rated current load.0.3A per contact.                                                                                                                                         |                     |
| 7.Vibration Sinusoidal Low Frequency     |      | No electrical discontinuity greater then 1 μsec (s) shall occur. Contact resistance:100 mΩ max.                        |             | Subject mated connector to 10-55-10 Hz traversed in 1 minute at 1.5 mm amplitude 2 hours each of 3 mutually perpendicular plane, 10 mA applied MIL-STD-202, Method 201.            |                     |
| 8. Shock                                 |      | No electrical discontinuity greater than 1 μsec. shall occur. No damage to product.                                    |             | Applying an appropriate holder is allowed in vibration test and shock test. MIL-STD-202, Method 213,490m/s2, 3 axes.                                                               |                     |
| Approved by:                             | Zeng |                                                                                                                        | Checked by: | JianZhong.Chen                                                                                                                                                                     | Prepared by: A-Zong |

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| Part Number                       |      | Product Name                                                                                                                                                                                      |             | Rev                                                                                                                                                                                        | Page No             |
|-----------------------------------|------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------|
| FTFXX-XXXXXXX-XXX                 |      | TF card push connector                                                                                                                                                                            |             | A                                                                                                                                                                                          | 7/9                 |
| TABLE I: PERFORMANCE REQUIREMENTS |      |                                                                                                                                                                                                   |             |                                                                                                                                                                                            |                     |
| 9. Thermal shock                  |      | No damage, Contact Resistance (Low Level) (Final) 100 mΩ max.                                                                                                                                     |             | Temperature range from -55° C to +85° C .Start from -55° C. After 30 min. change to +85° C, change time is no more than 30 seconds. Total 5 cycles. MIL-STD-202, Method 107D, condition A. |                     |
| 10. Humidity                      |      | No damage, Contact Resistance (Low Level) (Final) 100 mΩ max.. Dielectric Strength should be OK, Insulation Resistance should be 100 MΩ min.                                                      |             | Temperature :40±2° C 96 hours. Relative humidity: 90-95%; Duration: 96 Hours. MIL-STD-202, Method 103,                                                                                     |                     |
| 11.Solderability                  |      | Appearance of the specimen shall be inspected after the test with the assistance of a magnifier capable of giving a magnification of 10 X for any damage such as pinholes, void or rough surface. |             | Soldering time: 3 to 5 Seconds<br>Temperature: 245±5° C.                                                                                                                                   |                     |
| 12.Resistance to soldering heat   |      | No damage                                                                                                                                                                                         |             | Leave subject product in the 260±5° C chamber for 2 minutes.                                                                                                                               |                     |
| 13. Salt Spray                    |      | Contact Resistance (Low Level) (Final) 100 mΩ max.                                                                                                                                                |             | 5±1% salt concentration 12±2 hours 35±2° C MIL-STD-202, Method 101 Condition B. .                                                                                                          |                     |
| 14.High temperature               |      | Contact resistance: 100 mΩ max.                                                                                                                                                                   |             | Subject product to 85±2° C for 96 hours continuously. MIL-STD-202, Method 108.                                                                                                             |                     |
| Approved by:                      | Zeng |                                                                                                                                                                                                   | Checked by: | JianZhong.Chen                                                                                                                                                                             | Prepared by: A-Zong |

|                   |                        |     |         |
|-------------------|------------------------|-----|---------|
| Part Number       | Product Name           | Rev | Page No |
| FTFXX-XXXXXXX-XXX | TF card push connector | A   | 8/9     |

TABLE II: PRODUCT QUALIFICATION TEST SEQUENCE

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|-----------------------------------------------|------------|-----|-----|-----|-----|-----|
| Test Description                              | Test Group |     |     |     |     |     |
|                                               | A          | B   | C   | D   | E   | F   |
| Appearance                                    | 1,6        | 1,3 | 1,5 | 1,6 | 1,5 | 1,3 |
| Contact Resistance                            | 2          |     | 2,4 | 2,5 | 2,4 |     |
| Insulation Resistance                         | 3          |     |     | 3   |     |     |
| Dielectric Withstanding Voltage               |            | 2   |     |     |     |     |
| Durability                                    |            |     | 3   |     |     |     |
| Mating Force                                  | 4          |     |     |     |     |     |
| Un mating Force                               | 5          |     |     |     |     |     |
| Humidity Resistance                           |            |     |     | 4   |     |     |
| Salt Spray                                    |            |     |     |     | 3   |     |
| Solderability                                 |            |     |     |     |     | 2   |

|              |      |             |                |              |        |
|--------------|------|-------------|----------------|--------------|--------|
| Approved by: | Zeng | Checked by: | JianZhong.Chen | Prepared by: | A-Zong |
|--------------|------|-------------|----------------|--------------|--------|

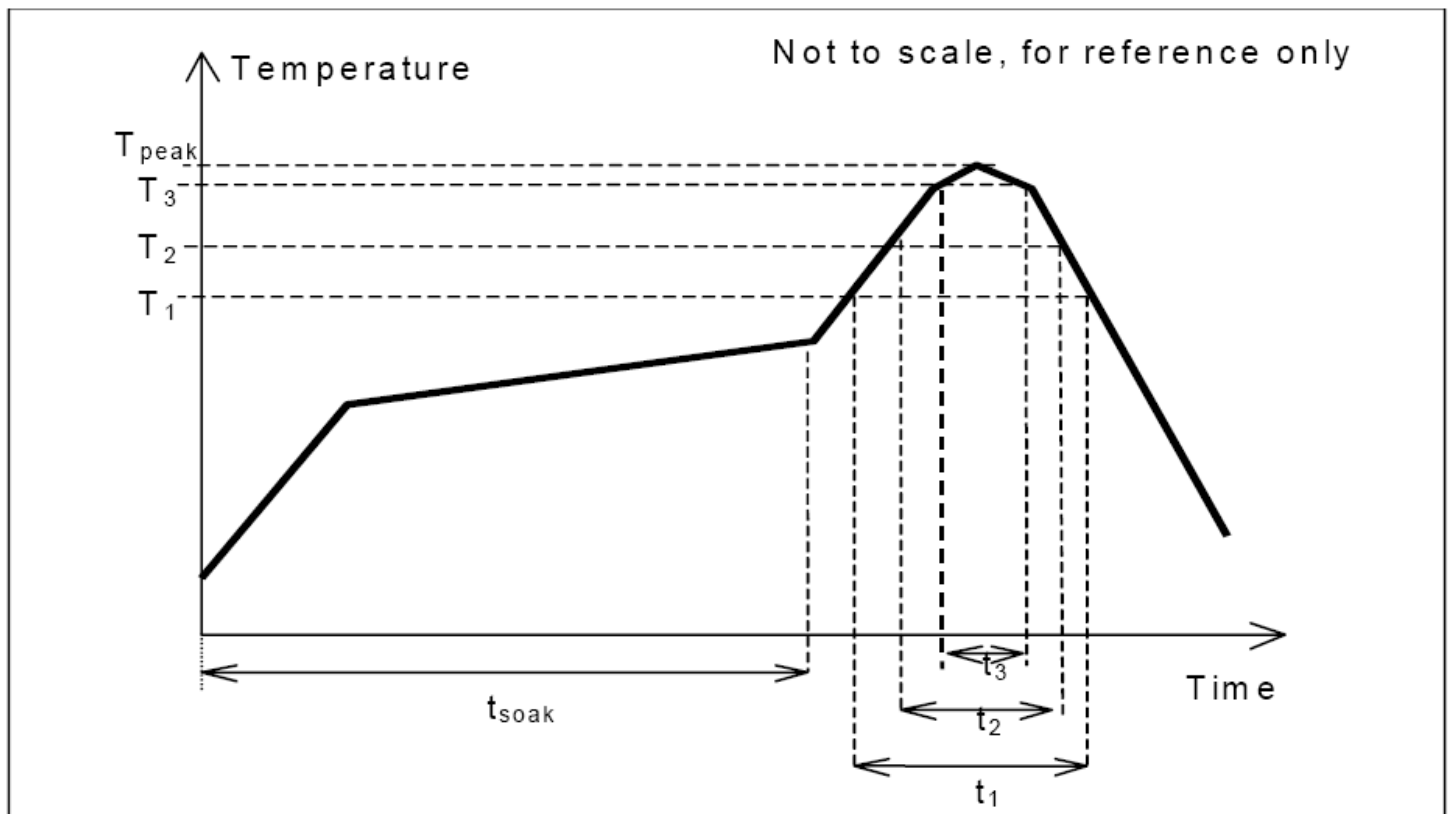
东莞市轻平电子科技有限公司  
Dongguan Qingping Electronic Technology Co., Ltd.

| Part Number       | Product Name           | Rev | Page No |
|-------------------|------------------------|-----|---------|
| FTFXX-XXXXXXX-XXX | TF card push connector | A   | 9/9     |

TABLE III:REFLOW SOLDERING PROFILE

Pb-free reflow profile requirements:

| Parameter                                  | Reference | Specification    |
|--------------------------------------------|-----------|------------------|
| Average temperature gradient in preheating |           | 2.5° C/s         |
| Soak time                                  | tsoak     | 2-3 minutes      |
| Time above 217° C                          | t1        | 60 s             |
| Time above 230° C                          | t2        | 50 s             |
| Time above 245° C                          | t3        | 5 s              |
| Peak temperature in reflow                 | Tpeak     | 250° C (+/-5° C) |
| Temperature gradient in cooling            |           | Max -5° C/s      |



This profile is the minimum requirement for evaluating soldering heat resistance of components. Heat transfer method used for reflow soldering is hot air convection. The actual air temperatures used to achieve the specified profile is higher and largely dependent on the reflow equipment.

|              |      |             |                |              |        |
|--------------|------|-------------|----------------|--------------|--------|
| Approved by: | Zeng | Checked by: | JianZhong.Chen | Prepared by: | A-Zong |
|--------------|------|-------------|----------------|--------------|--------|